

Product Summary

| $V_{(BR)DSS}$ | $R_{DS(on)TYP}$ | I_D |
|---------------|-----------------|-------|
| 500V | 1.2Ω@10V | 5A |

Features

- Very Low On-resistance RDS(ON)
- LowCrss
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Applications

- Switch Mode Power Supply
- Uninterruptible Power Supply (UPS)
- TV Power
- Adapter/Charger

500V N-channel planar MOSFET

| TO-252 |
|--|
| |
| PIN1:GATE PIN2:DRAIN PIN3:SOURCE |
| Schematic diagram |
| |
| Marking |
| |
| 5N50 : Device Code YY : Year Code WW : Week Code |

Absolute Maximum rating ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | | Symbol | Value | Units |
|---|---------------------------|-----------------|-------------|---------------------------|
| Drain-Source Voltage | | V_{DSS} | 500 | V |
| Drain Current | $T_c = 25^\circ\text{C}$ | I_D | 5 | A |
| | $T_c = 100^\circ\text{C}$ | | 35 | A |
| Drain Current - Pulsed | | I_{DM} | 20 | A |
| Gate-Source Voltage | | V_{GSS} | ± 30 | V |
| Single Pulsed Avalanche Energy ¹ | | E_{AS} | 300 | mJ |
| Power Dissipation | $T_c = 25^\circ\text{C}$ | P_D | 48 | W |
| Thermal Resistance, Junction-to-Case | | $R_{\theta JC}$ | 2.6 | $^\circ\text{C}/\text{W}$ |
| Operating and Storage Temperature Range | | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ |

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|--------------------------|--|-----|------|-----------|---------------|
| Off Characteristics | | | | | | |
| Drain - Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$ | 500 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = 500\text{V}, V_{\text{GS}} = 0\text{V}$ | | | 1 | μA |
| Gate - Body Leakage Current | I_{GSS} | $V_{\text{GS}} = \pm 30\text{V}, V_{\text{DS}} = 0\text{V}$ | | | ± 100 | nA |
| Gate Threshold Voltage | $V_{\text{GS(th)}}$ | $V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$ | 2 | 3 | 4 | V |
| Drain-source On-resistance | $R_{\text{DS(on)}}$ | $V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 2.5\text{A}$ | | 1.2 | 1.5 | Ω |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$ | | 488 | | pF |
| Output Capacitance | C_{oss} | | | 60 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 7.2 | | |
| Switching Characteristics | | | | | | |
| Total Gate Charge | Q_g | $V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 400\text{V}, I_{\text{D}} = 5\text{A}$ | | 16.5 | | nC |
| Gate-source Charge | Q_{gs} | | | 3.8 | | |
| Gate-drain Charge | Q_{gd} | | | 5.6 | | |
| Turn-on Delay Time | $t_{\text{d(on)}}$ | $V_{\text{DD}} = 250\text{V}, I_{\text{D}} = 5\text{A}, R_{\text{G}} = 10\Omega, V_{\text{GS}} = 10\text{V}$ | | 14 | | ns |
| Turn-on Rise Time | t_r | | | 18 | | |
| Turn-off Delay Time | $t_{\text{d(off)}}$ | | | 32 | | |
| Turn-off Fall Time | t_f | | | 11 | | |
| Source - Drain Diode Characteristics | | | | | | |
| Drain to Source Diode Forward Voltage | V_{SD} | $V_{\text{GS}} = 0\text{V}, I_{\text{SD}} = 5\text{A}, T_J = 25^\circ\text{C}$ | | | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $I_F = 5\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$ | | 328 | | ns |
| Reverse Recovery Charge | Q_{rr} | | | 1.6 | | μC |

Note:

1. E_{AS} condition: L=24mH, ID=5A, RG=25Ω, VDD=100V, Start T_J=25°C

ASIC Micro-Electronics Limited

Typical Characteristic

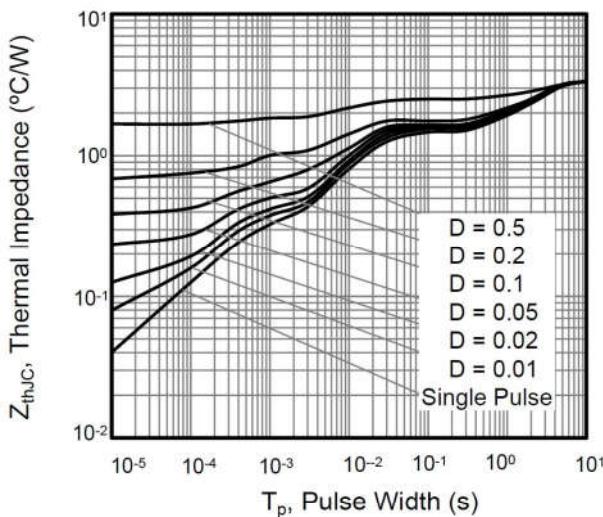


Figure 1. Transient Thermal Impedance For TO-220F

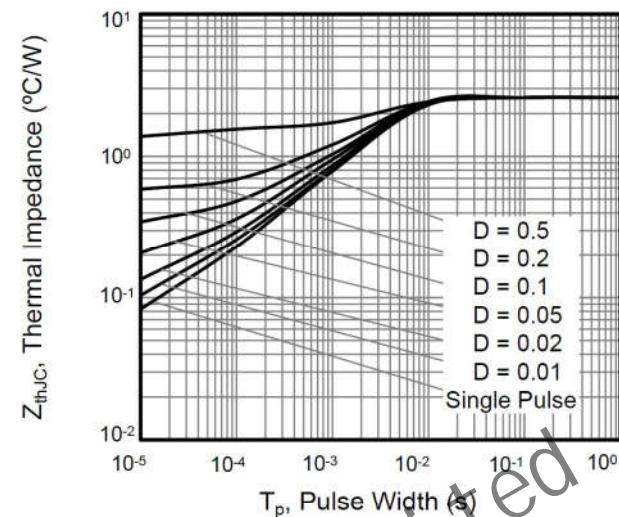


Figure 2. Transient Thermal Impedance For TO-220, TO-263, TO-252, TO-251

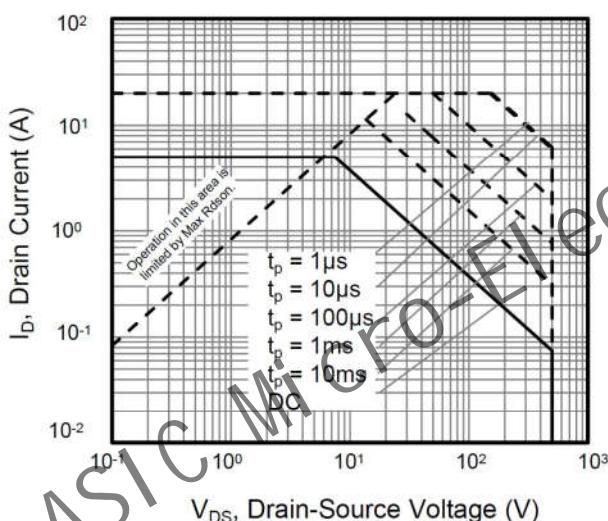


Figure 3. Safe Operation Area For TO-220F

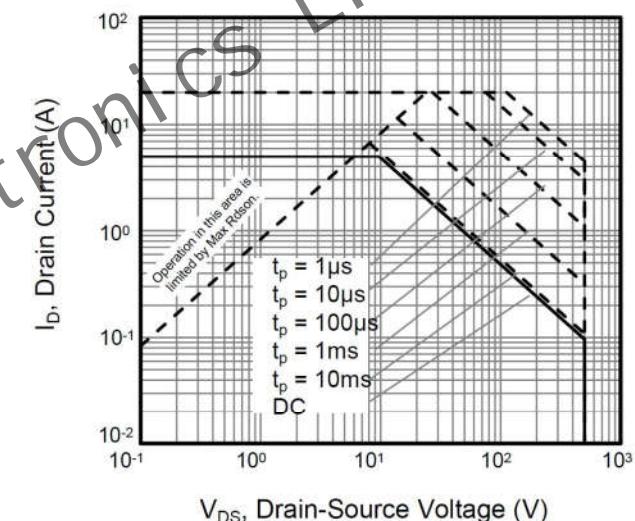


Figure 4. Safe Operation Area For TO-220, TO-263, TO-252, TO-251

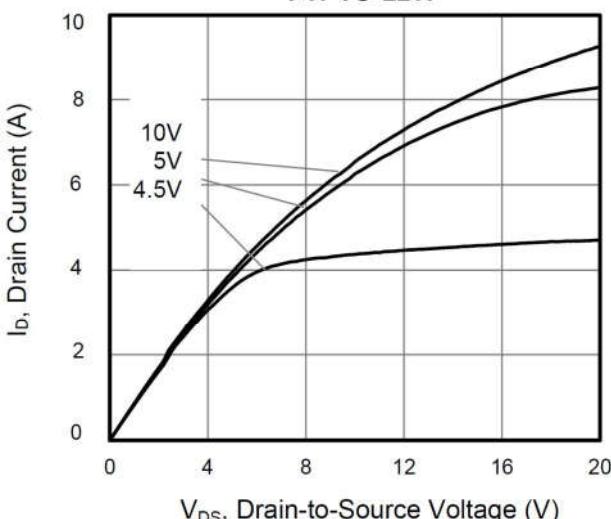


Figure 5. Output Characteristics

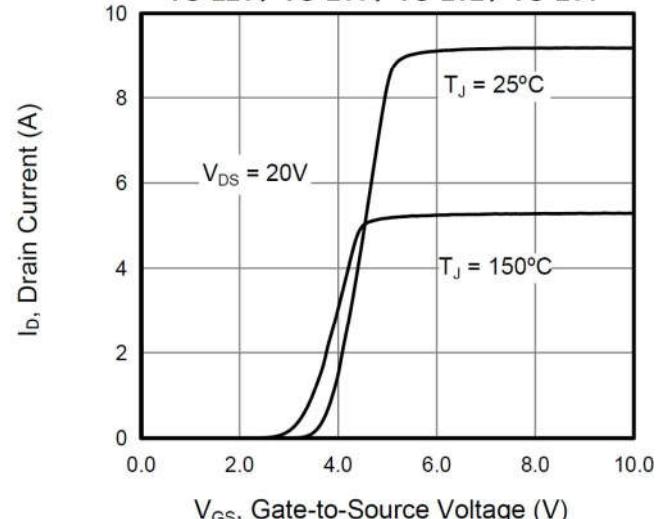


Figure 6. Transfer Characteristics

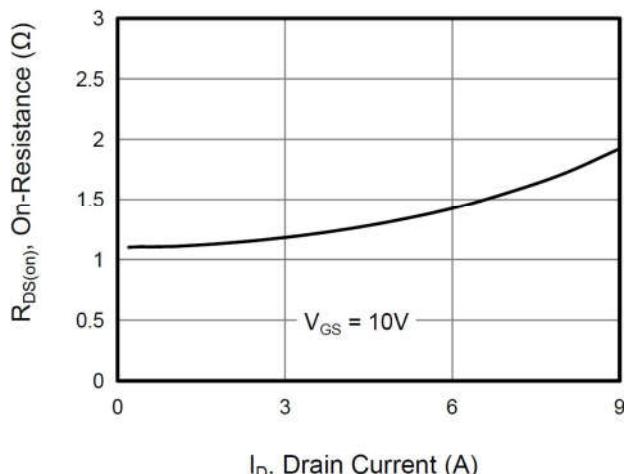


Figure 7. On-Resistance vs Drain Current

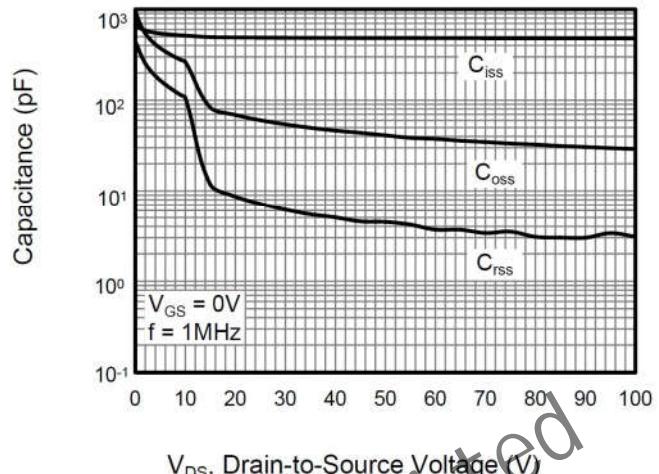


Figure 8. Capacitance

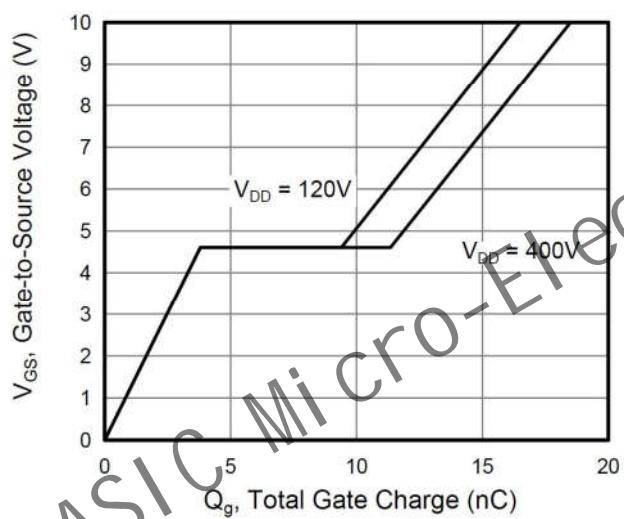


Figure 9. Gate Charge

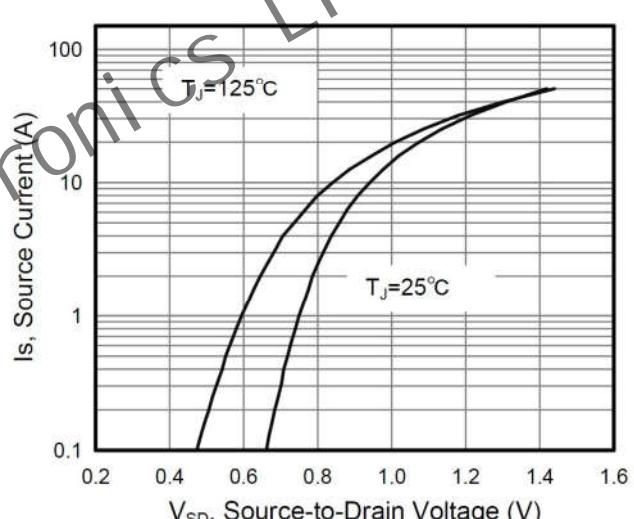


Figure 10. Body Diode Forward Voltage

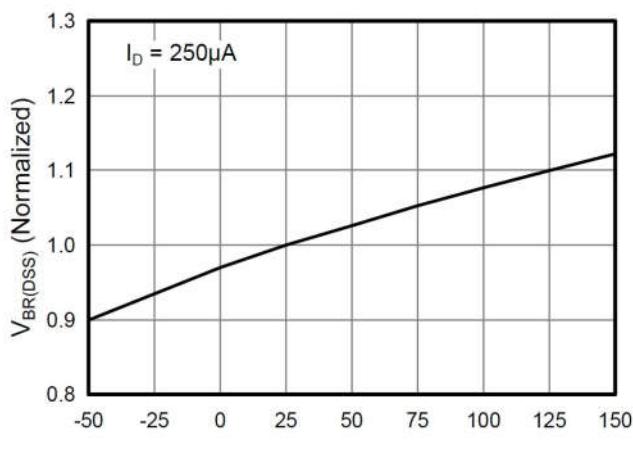


Figure 11. Breakdown Voltage vs Junction Temperature

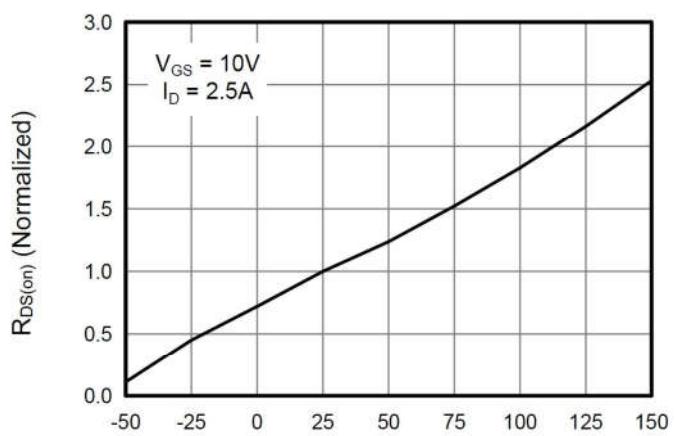
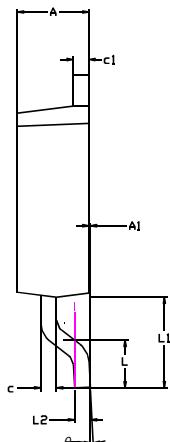
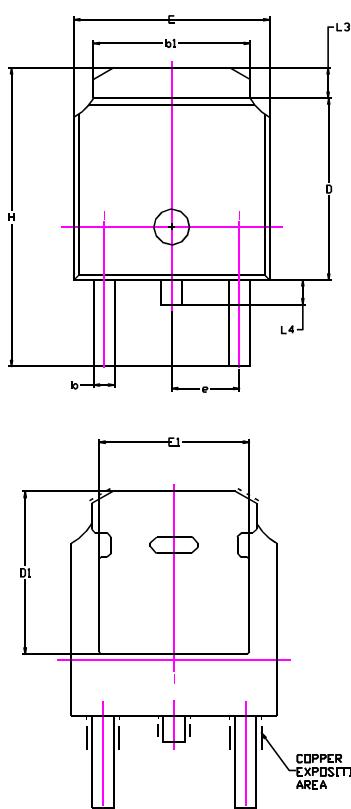


Figure 12. On-Resistance vs Temperature

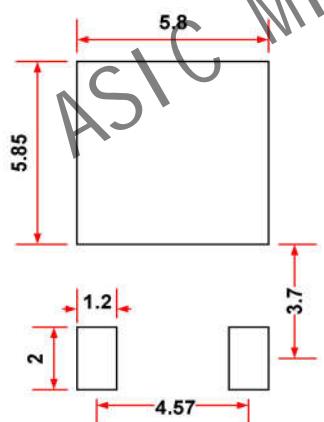
Dimension

TO252



| Symbol | Millimeters | | |
|----------|-------------|-------|----------|
| | Min. | Max. | Min. |
| A | 2.20 | 2.40 | A |
| A1 | 0.00 | 0 | A1 |
| b | 0. | 0.77 | b |
| b1 | 5.17 | 5.42 | b1 |
| c | 0.46 | 0.60 | c |
| c1 | 0.46 | 0.58 | c1 |
| D | 6.00 | 6.20 | D |
| D1 | | 5.15 | D1 |
| E | 6.50 | 6.70 | E |
| E1 | | 4.83 | E1 |
| e | | 2.286 | e |
| H | 9.40 | 1 | H |
| L | 1.40 | 1.70 | L |
| L1 | | 2.90 | L1 |
| L2 | | 0.508 | L2 |
| L3 | 0.89 | 1.27 | L3 |
| L4 | 0.64 | 1.01 | L4 |
| θ | 0° | 10° | θ |

Recommended Land Pattern



Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference only
4. Unit: mm